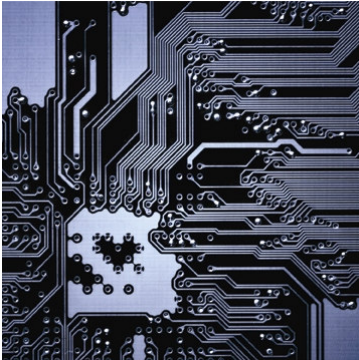


Tinposit™ LF Immersion Tin

The latest in immersion tin technology providing high reliability and solderability for interconnect applications

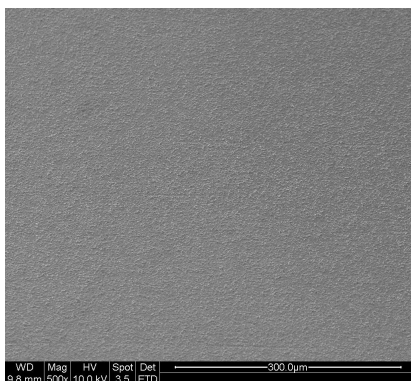


Tinposit™ LF Immersion Tin produces uniform and solderable tin deposits on properly prepared PWB substrates and is specifically formulated to be used in lead-free assembly processes. The deposits can maintain good solderability after multiple reflow processes. The Tinposit™ LF Immersion Tin bath is easy to control and has a high tolerance for contaminants.

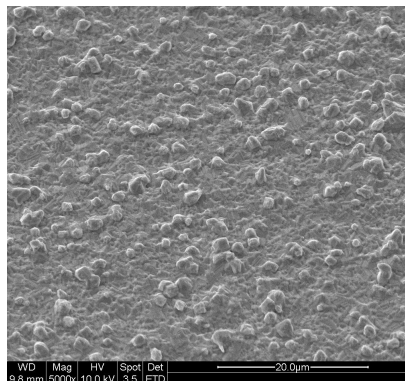
Advantages

- Maintains excellent solderability after multiple lead-free PCB assembly reflow cycles, improving manufacturing process capability and yield;
- Outstanding solder joint reliability, resulting from excellent bonding force between PCB pad and reflowed solder paste;
- No tin whisker formation, increasing product reliability and avoiding short-circuits between closely spaced circuit features;
- Effectively eliminates galvanic corrosion preventing yield loss from circuit breaks;
- Significantly reduced attack on solder mask

Immersion tin surface SEM showing that there is no tin whisker formation



X 500



X 5000